## **10/536652** JC20 Rec'd PCT/PTO 2 7 MAY 2005

## **Application Data Sheet**

**Application Information** 

Application Type:

Regular

Subject Matter:

Utility

Suggested Classification:

Suggested Group Art Unit:

CD-ROM or CD-R?:

None

Title:

Attachment of Flip-Chips to Substrates

Request for Early Publication?:

No

Request for Non-Publication?:

No

Suggested Drawing Figure:

. 4

**Total Drawing Sheets:** 

4

Small Entity:

No

Petition included?:

No

Secrecy Order in Parent Appl.?:

No

**Applicant Information** 

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**Representative Information** 

Representative Customer Number:	000050255		

## **Domestic Priority Information**

Application:	Continuity Type:	Parent Application:	Parent Filing Date:
	National Stage Of	PCT/SG2002/000282	29 November 2002

## **Assignee Information**

Assignee name:

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